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RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE - EXAMINING GROUP 1700

PATENT

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November 17, 2006

Date

Denise Sheridan

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 09/974,958 Confirmation No. : 7582
Applicants : Vernon M. Williams et al.
Filed : October 10, 2001 Attorney Docket No.: 501062.01
Art Unit : 1722 Customer No. : 27,076
Examiner : Robert B. Davis
Title : LEADFRAME AND METHOD FOR REDUCING MOLD COMPOUND ADHESION PROBLEMS

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Sir:

Applicants acknowledge receipt of the Office Action dated September 7, 2006.

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the Drawings begin on page 8 of this paper and include both annotated and replacement sheets.

Remarks begin on page 9 of this paper.

An Appendix including amended drawing figures is attached following page 12 of this paper.